

**RETURN BIDS TO:**  
**RETOURNER LES SOUMISSIONS À:**  
**Bid Receiving - PWGSC / Réception des soumissions -**  
**TPSGC**  
**11 Laurier St./ 11 rue, Laurier**  
**Place du Portage, Phase III**  
**Core 0A1 / Noyau 0A1**  
**Gatineau, Québec K1A 0S5**  
**Bid Fax: (819) 997-9776**

## **SOLICITATION AMENDMENT MODIFICATION DE L'INVITATION**

The referenced document is hereby revised; unless otherwise indicated, all other terms and conditions of the Solicitation remain the same.

Ce document est par la présente révisé; sauf indication contraire, les modalités de l'invitation demeurent les mêmes.

### **Comments - Commentaires**

**Vendor/Firm Name and Address**  
**Raison sociale et adresse du**  
**fournisseur/de l'entrepreneur**

**Issuing Office - Bureau de distribution**  
Scientific, Medical and Photographic Division /  
Division de l'équipement scientifique, des produits  
photographiques et pharmaceutiques  
11 Laurier St./ 11 rue, Laurier  
6B1, Place du Portage  
Gatineau, Québec K1A 0S5

<b>Title - Sujet</b> X-Ray Computed Tomography System	
<b>Solicitation No. - N° de l'invitation</b> 4M033-130069/A	<b>Amendment No. - N° modif.</b> 001
<b>Client Reference No. - N° de référence du client</b> 4M033-130069	<b>Date</b> 2013-08-27
<b>GETS Reference No. - N° de référence de SEAG</b> PW-\$\$PV-890-63289	
<b>File No. - N° de dossier</b> pv890.4M033-130069	<b>CCC No./N° CCC - FMS No./N° VME</b>
<b>Solicitation Closes - L'invitation prend fin</b> <b>at - à 02:00 PM</b> <b>on - le 2013-09-24</b>	<b>Time Zone</b> <b>Fuseau horaire</b> Eastern Daylight Saving Time EDT
<b>F.O.B. - F.A.B.</b> <b>Plant-Usine:</b> <input type="checkbox"/> <b>Destination:</b> <input checked="" type="checkbox"/> <b>Other-Autre:</b> <input type="checkbox"/>	
<b>Address Enquiries to: - Adresser toutes questions à:</b> Hennessey, Lisa	<b>Buyer Id - Id de l'acheteur</b> pv890
<b>Telephone No. - N° de téléphone</b> (819) 956-9001 ( )	<b>FAX No. - N° de FAX</b> ( ) -
<b>Destination - of Goods, Services, and Construction:</b> <b>Destination - des biens, services et construction:</b>	

**Instructions: See Herein**

**Instructions: Voir aux présentes**

<b>Delivery Required - Livraison exigée</b>	<b>Delivery Offered - Livraison proposée</b>
<b>Vendor/Firm Name and Address</b> <b>Raison sociale et adresse du fournisseur/de l'entrepreneur</b>	
<b>Telephone No. - N° de téléphone</b> <b>Facsimile No. - N° de télécopieur</b>	
<b>Name and title of person authorized to sign on behalf of Vendor/Firm</b> <b>(type or print)</b> <b>Nom et titre de la personne autorisée à signer au nom du fournisseur/</b> <b>de l'entrepreneur (taper ou écrire en caractères d'imprimerie)</b>	
<b>Signature</b>	<b>Date</b>

Solicitation Amendment 001 has been raised to answer the following Bidder questions:

**Q1. Do you need a 'contrast injector'?**

A1. No, we do not need a contract injector.

**Q2. What type of samples will be inspected with this system?**

A2. Samples range from very small requiring very high resolution to large requiring fairly high resolution. Type of samples we will be inspecting are:

- (small) Microchips - to look at wire bonds
- Circuit boards
- Electronic units - full GPS units and electronic systems such as cockpit displays, etc
- Wire/cable bundles
- (large) Cast metal housings - hydraulic pumps, engine crank cases, etc
- Actuators/servos
- documentation of the as-received condition of components
- examination of material failures (fractures and cracks, voids in case aluminum or magnesium housing, welding/brazing defects)
- examination of internal passages to look for blockages/holes (oil slingers, hoses, hydraulic lines)
- examination of system components to look for internal failures, relative position of parts (switches, gear analysis, light bulbs, valves...)
- examination of solder joint and components on circuit boards from all modes (ELTs, aircraft instruments, ship electrical control systems, connectors/wiring from locomotive electrical systems)
- examination of components during non-volatile memory (NVM) recovery (NVM chip recovery techniques requires that circuit board damage be repaired and the unit returned to a functional state for data recovery)
- examination of wires and connectors for indications of arcing and poor contact (for example in locomotive distribution system)
- examination of burnt components embedded within melted material
- examination of cord/belt material in tires
- examination of composite damage/delamination

**Q3. Will you provide samples for testing to ensure the application is suitable?**

A3. We are confident that any unit that meets the mandatory technical specifications identified at Annex B will meet our needs; therefore we will not be sending out any samples for testing.

**All other terms and conditions remain the same**